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(12) **United States Design Patent**
Itakura et al.

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- (54) **SEMICONDUCTOR PACKAGE**
- (71) Applicant: **Mitsubishi Electric Corporation**,
Tokyo (JP)
- (72) Inventors: **Hiroshi Itakura**, Tokyo (JP); **Keitaro Yamagishi**, Tokyo (JP); **Yoshihiro Akeboshi**, Tokyo (JP)
- (73) Assignee: **Mitsubishi Electric Corporation**,
Tokyo (JP)
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- (51) **LOC (12) Cl.** **13-03**
- (52) **U.S. Cl.**
USPC **D13/182**
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361/775, 783, 820; 174/250, 253;
438/15, 25, 26, 51, 55, 63, 64, 106
CPC . H01L 21/00; H01L 2224/42; H01L 2224/43;
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2924/1905; H01L 2224/08054; H01L

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G02B 6/4262; G02B 6/428; G02B
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1/142; H05K 1/144; H05K 1/18; H05K
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See application file for complete search history.

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Primary Examiner — Elizabeth J Oswecki

(74) *Attorney, Agent, or Firm* — Studebaker & Brackett
PC

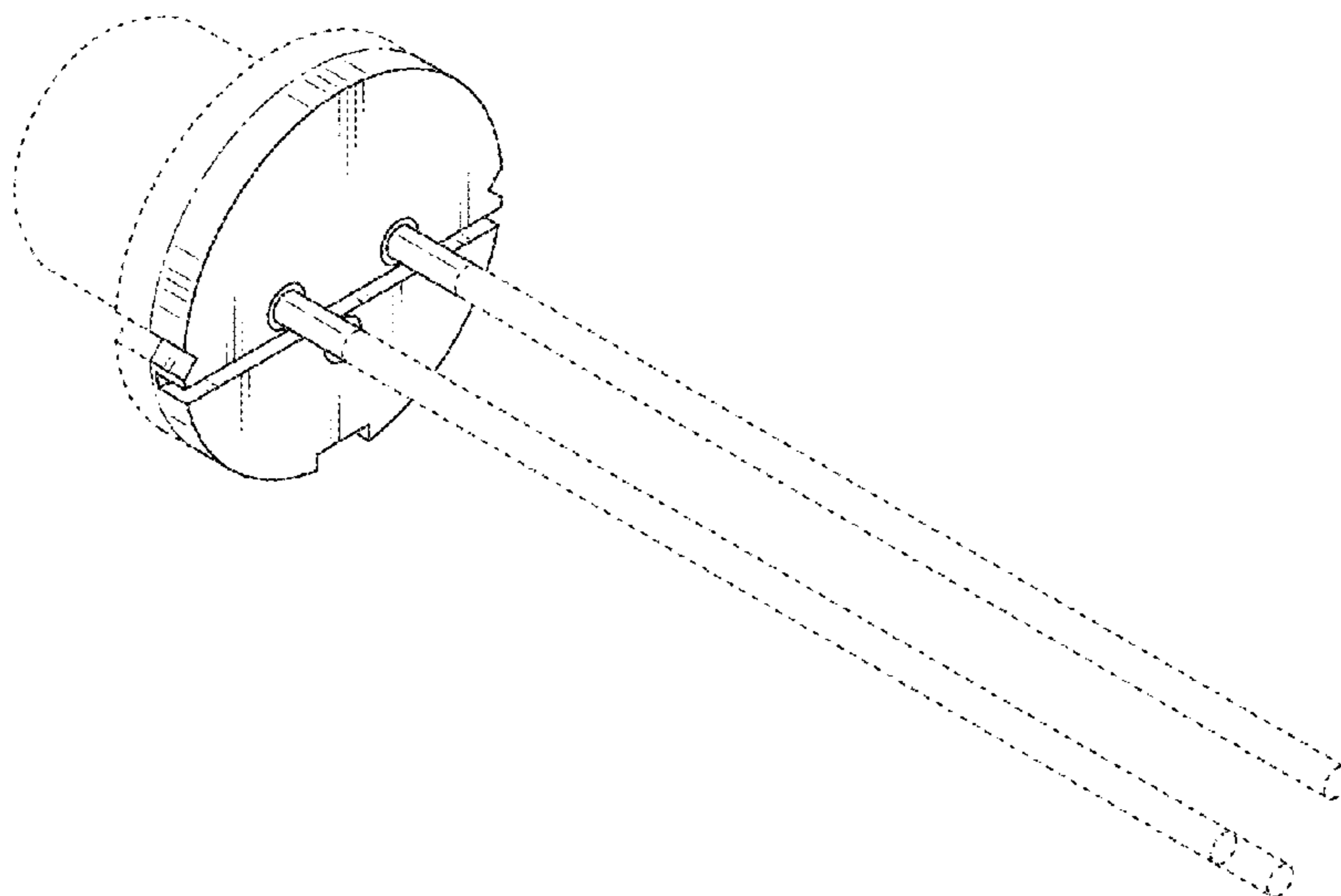
(57) **CLAIM**

The ornamental design for a semiconductor package, as shown and described.

DESCRIPTION

FIG. 1 is a front, top and left side perspective view of a semiconductor package showing our new design;
FIG. 2 is a front view thereof;
FIG. 3 is a rear view thereof;
FIG. 4 is a top view thereof;
FIG. 5 is a bottom view thereof;
FIG. 6 is a left side view thereof; the right side view being a mirror image thereof;
FIG. 7 is a cross sectional view taken along line 7-7 of FIG. 2, with the internal system omitted; and,
FIG. 8 is another perspective view thereof, showing the state in use.
The parts shown in even dashed broken lines do not form part of the claimed design.

1 Claim, 5 Drawing Sheets



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Fig. 1

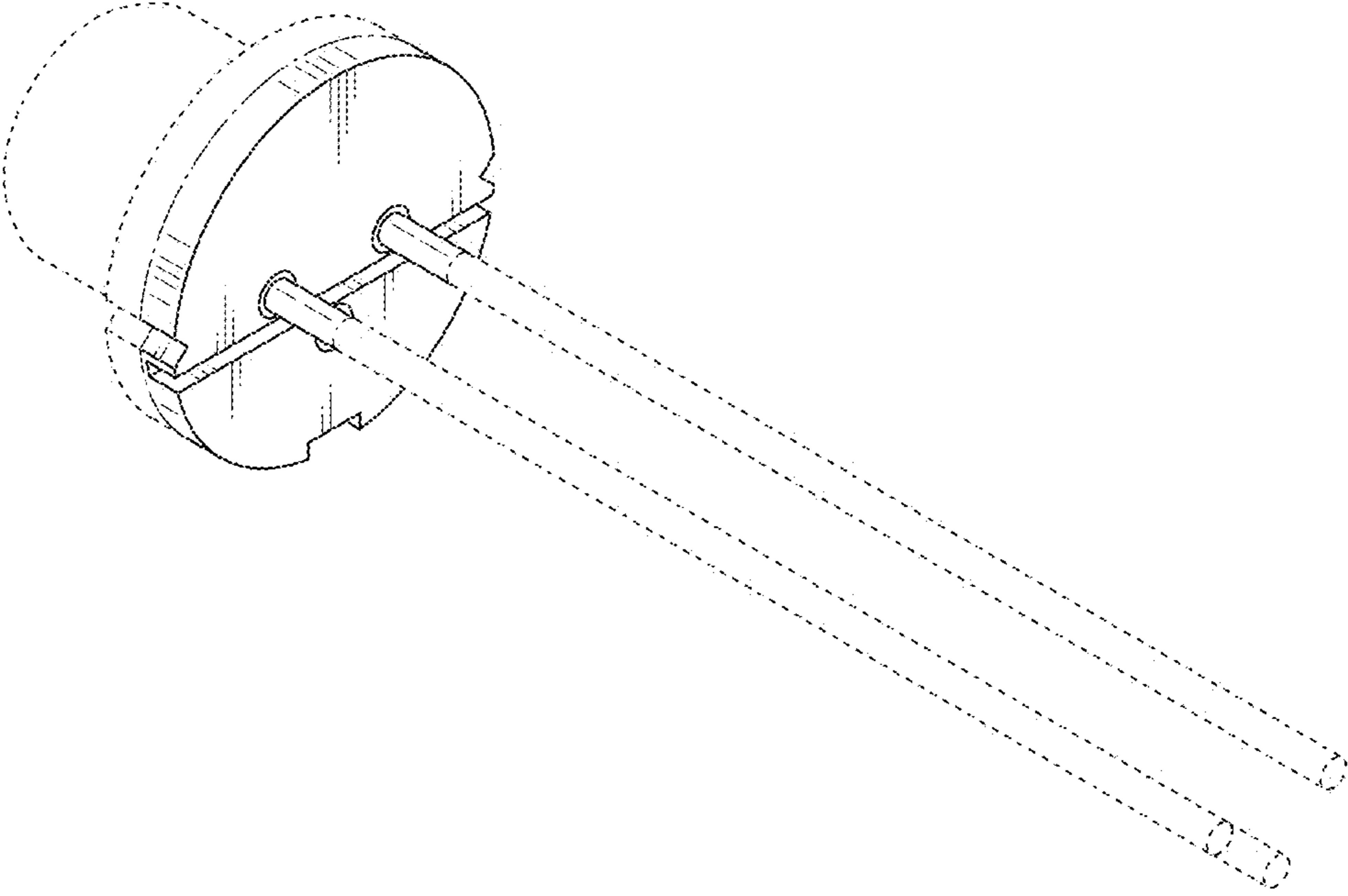


Fig. 2

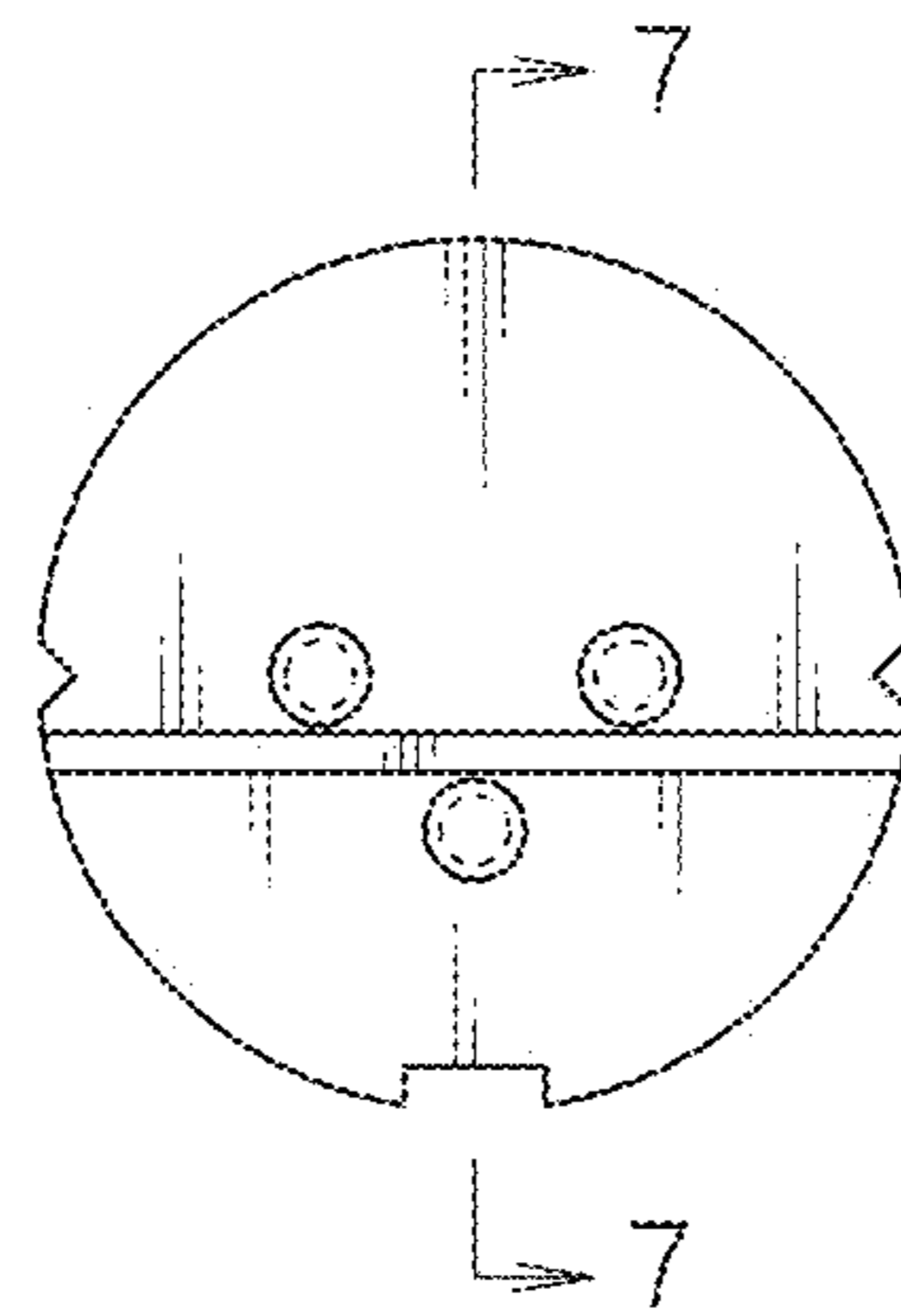


Fig. 3

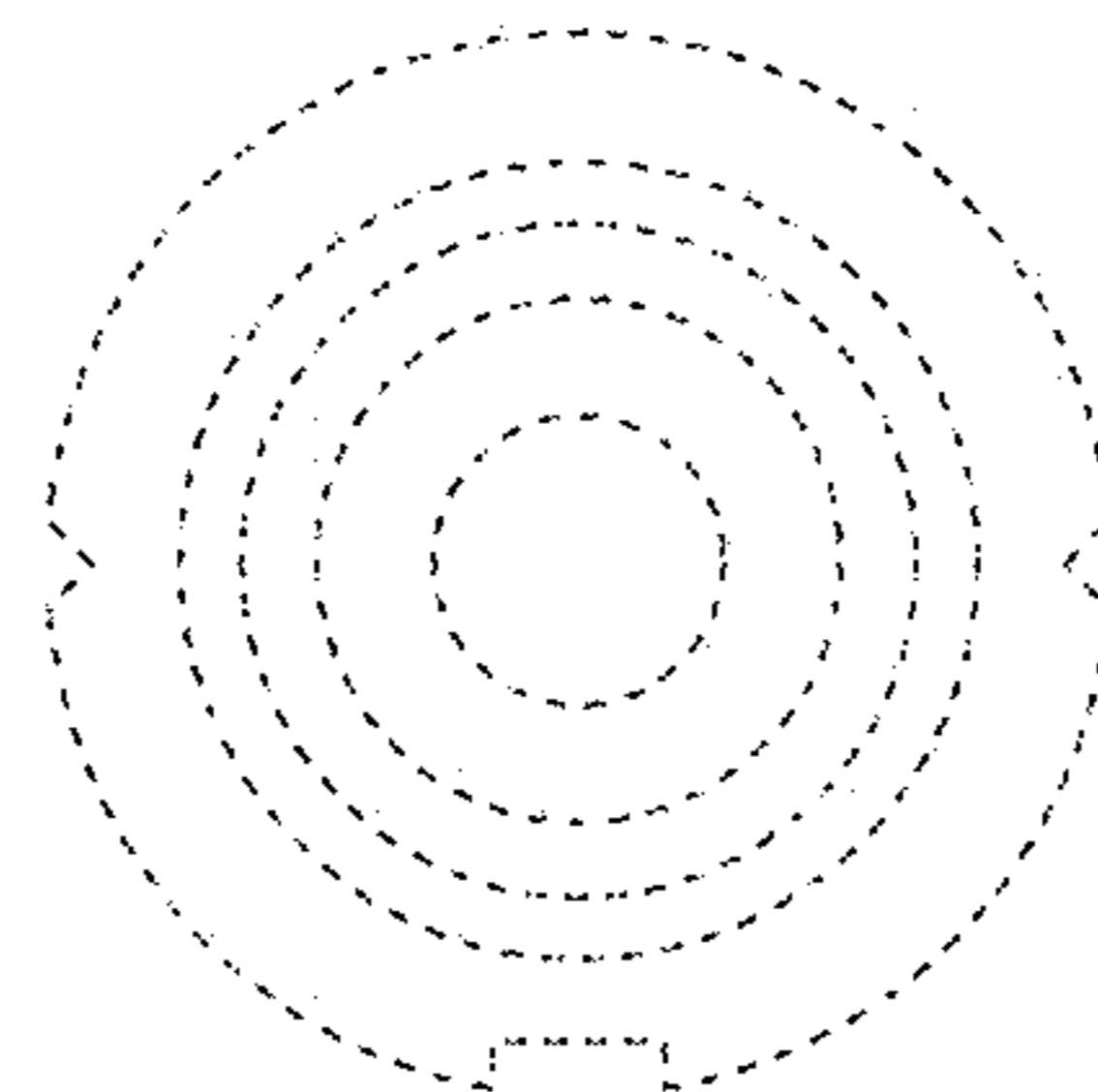


Fig. 4

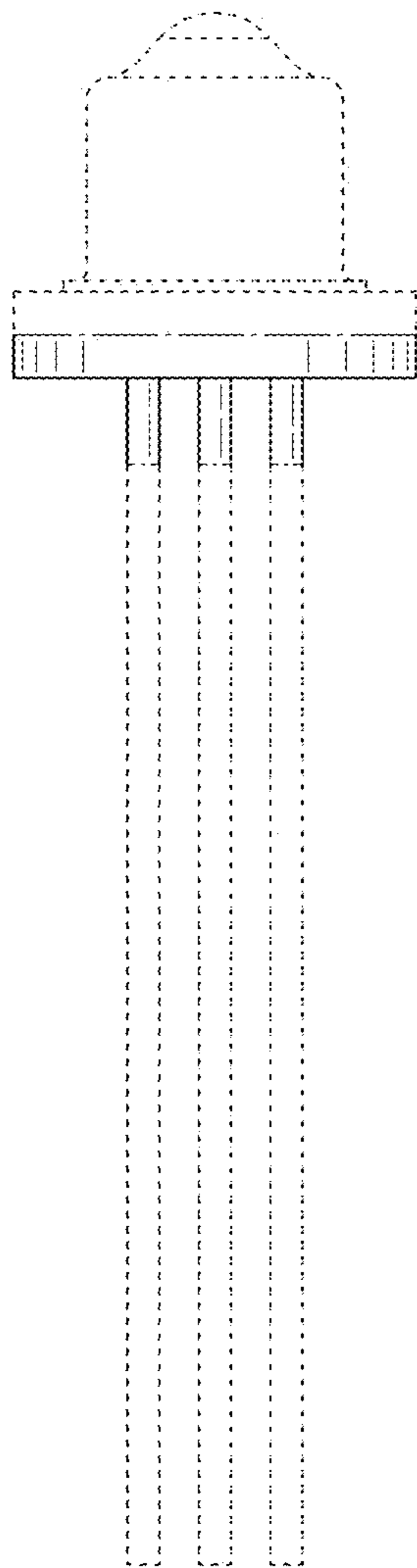


Fig. 5

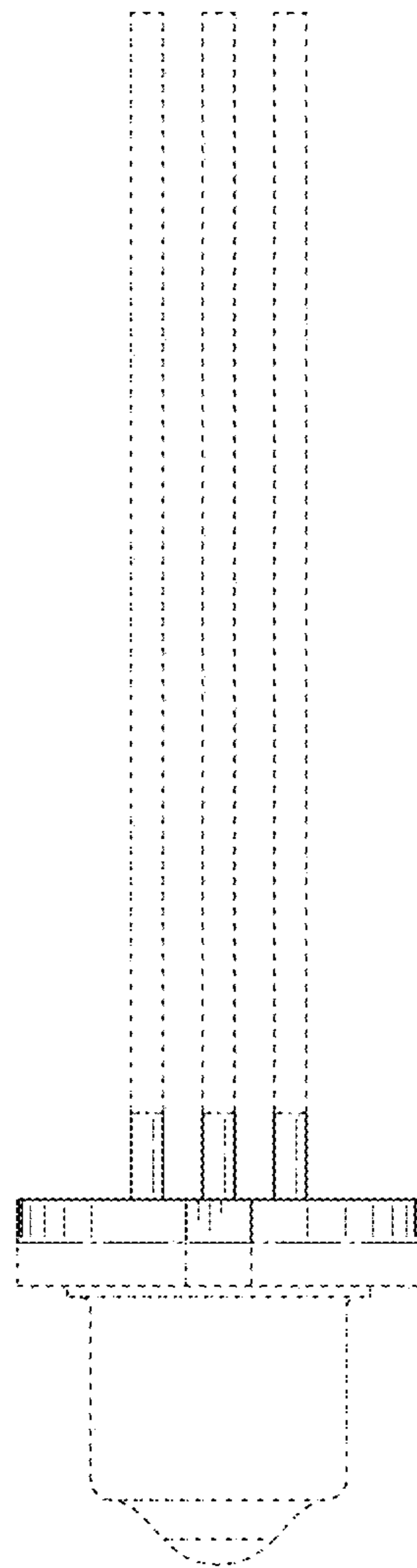


Fig. 6

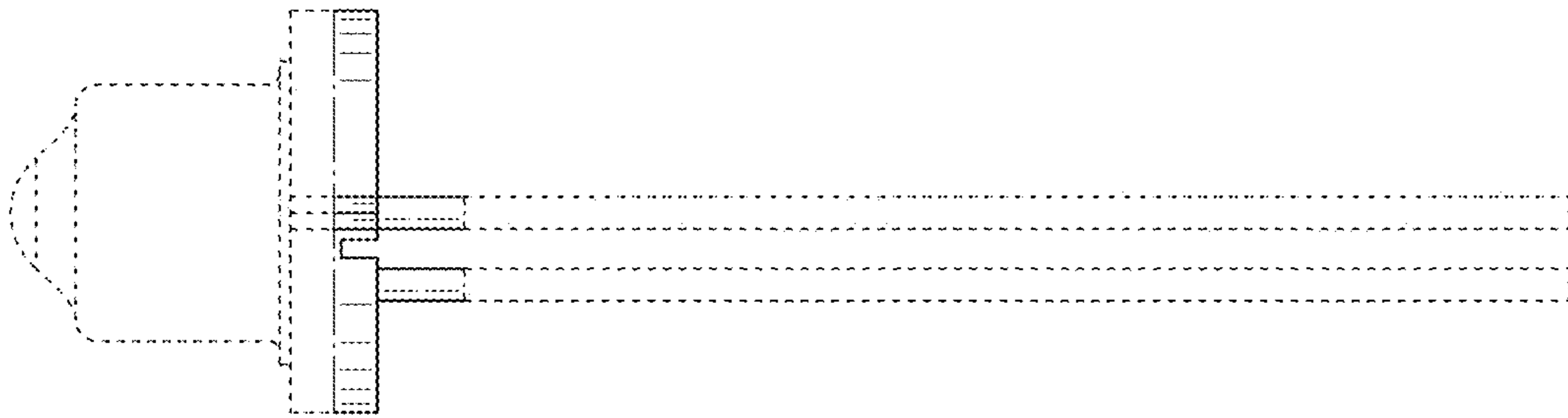


Fig. 7

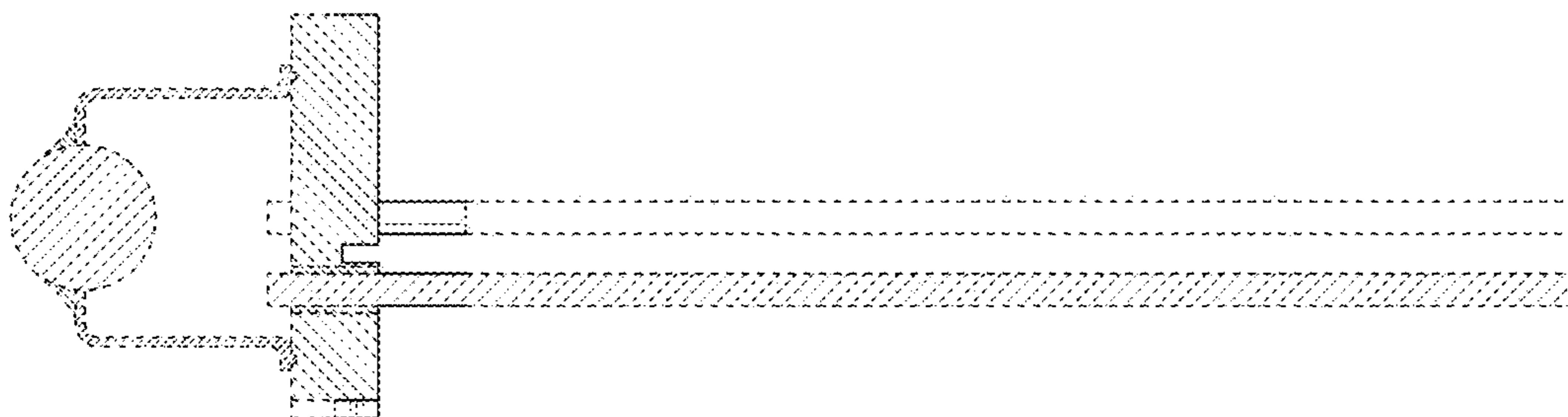


Fig. 8

